

(0.80 mm) .0315"

ZA8 SERIES

ULTRA LOW PROFILE MICRO ARRAYS

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?ZA8

Insulator Material: FR4

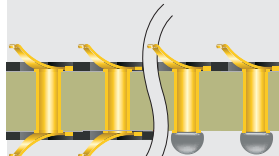
Contact Material: BeCu

Plating: Au over 50 μ" (1.27 μm) Ni
Operating Temp Range: -55 °C to +105 °C

Current Rating: .8 A per pin (10 pins powered)

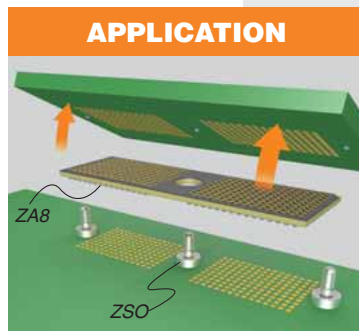
RoHS Compliant: Yes

APPLICATION



Dual compression or single compression with solder balls

OTHER SOLUTIONS

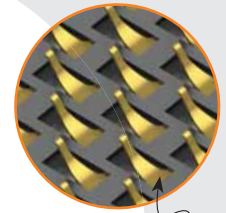


Note: Solder ball parts will come with a pick & place pad.

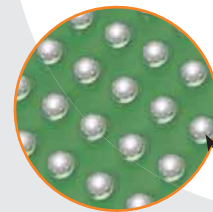
25 g normal force with (0.20 mm) .008" contact deflection

Up to 1,200 contacts/square inch

Dual compression or single compression with solder balls



28 Gbps



(1.00 mm) .040" height

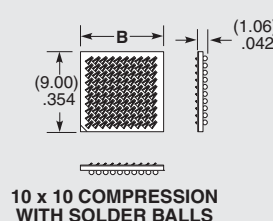
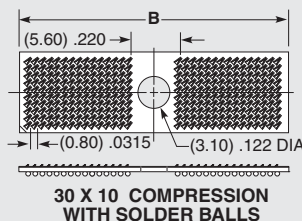
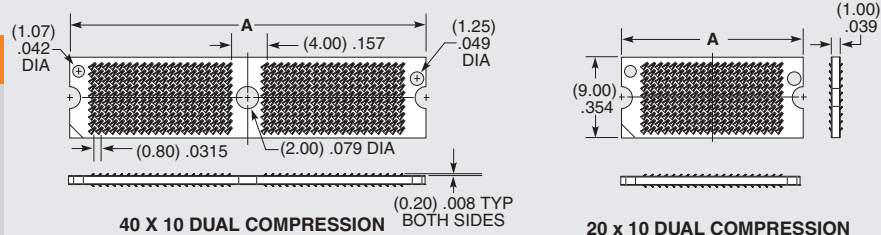
ZA8	POSITIONS PER ROW	TERMINATION	HEIGHT	PLATING	ROWS	SOLDER TYPE
	-10, -20, -30, -40	-1 = Single Compression with Solder Balls (-10 & -20 positions only) -2 = Dual Compression (-10, -20, -30 & -40 positions only)	-1.00 = (1.00 mm) .040" Height	-Z = 6 μ" (0.15 μm) Gold in contact area	-10 = Ten Rows	(Termination -1 only) -2 = Lead-Free

DESIGN FLEXIBILITY

The Z-Ray™ platform is highly-customizable:

PITCH	≥ 0.65 mm
STACK HEIGHT	0.50 mm to 4.00 mm
DENSITY	Up to 1,200 contacts/square inch
RUGGEDIZING	Latches, Thermal Spreaders, Quick-Release Spring Constraints
CONSTRUCTION	Multi-layer FR4 (e.g., Pitch Spreaders)

Contact Samtec.



POSITIONS PER ROW	A	B
-10	(12.50) .492	(9.35) .368
-20	(20.50) .807	(17.35) .683
-30	(31.70) 1.248	(30.15) 1.187
-40	(39.70) 1.563	(38.15) 1.502

Note: Some lengths, styles and options are non-standard, non-returnable.